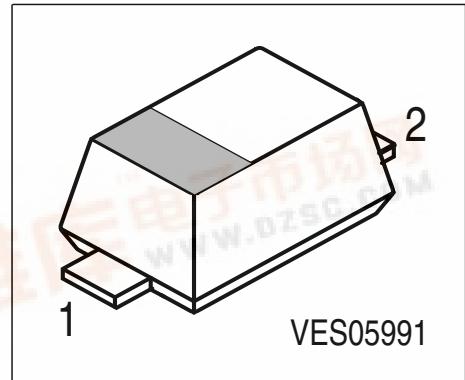


**BAS 16-02W****Silicon Switching Diode**

- For high-speed switching applications



Type	Marking	Pin Configuration		Package
BAS 16-02W	3	1 = C	2 = A	SCD-80

Maximum Ratings

Parameter	Symbol	Value	Unit
Diode reverse voltage	V_R	75	V
Peak reverse voltage	V_{RM}	85	
Forward current	I_F	200	mA
Surge forward current, $t = 1 \mu s$	I_{FS}	2.5	A
Total power dissipation, $T_S = 120^\circ C$	P_{tot}	250	mW
Junction temperature	T_j	150	$^\circ C$
Storage temperature	T_{stg}	-65 ... 150	

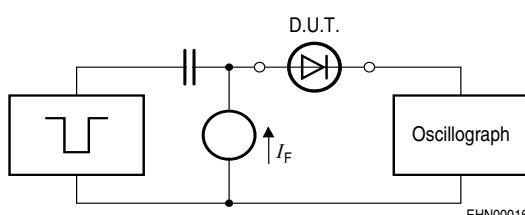
Thermal Resistance

Junction - ambient 1)	R_{thJA}	≤ 255	K/W
Junction - soldering point	R_{thJS}	≤ 120	

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC characteristics					
Breakdown voltage $I_{(\text{BR})} = 100 \mu\text{A}$	$V_{(\text{BR})}$	75	-	-	V
Forward voltage $I_F = 1 \text{ mA}$ $I_F = 10 \text{ mA}$ $I_F = 50 \text{ mA}$ $I_F = 150 \text{ mA}$	V_F	-	-	715	mV
		-	-	855	
		-	-	1000	
		-	-	1250	
Reverse current $V_R = 70 \text{ V}$	I_R	-	-	1	μA
Reverse current $V_R = 25 \text{ V}, T_A = 150^\circ\text{C}$ $V_R = 75 \text{ V}$	I_R	-	-	30	
		-	-	50	
AC characteristics					
Diode capacitance $V_R = 0 \text{ V}, f = 1 \text{ MHz}$	C_D	-	-	2	pF
Reverse recovery time $I_F = 10 \text{ mA}, I_R = 10 \text{ mA}, R_L = 100 \Omega$, measured at $I_R = 1 \text{ mA}$	t_{rr}	-	-	6	ns

Test circuit for reverse recovery time

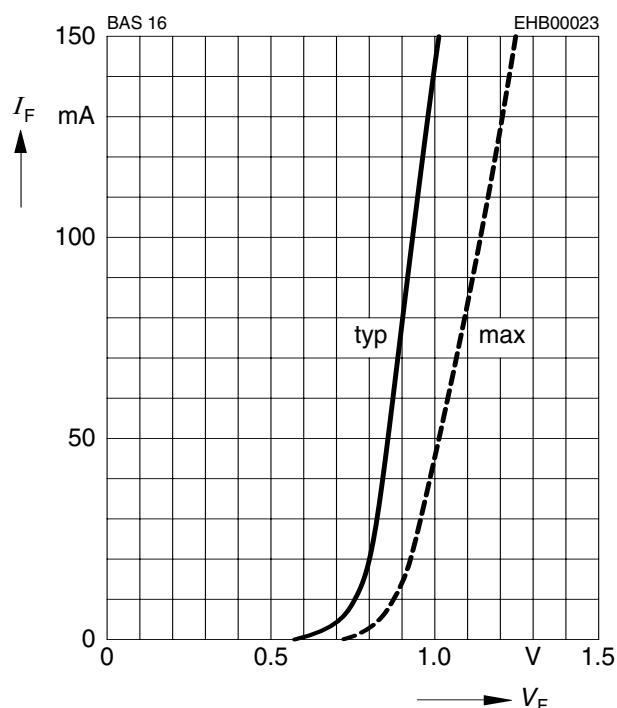


Pulse generator: $t_p = 100\text{ns}$, $D = 0.05$,
 $t_r = 0.6\text{ns}$, $R_i = 50\Omega$

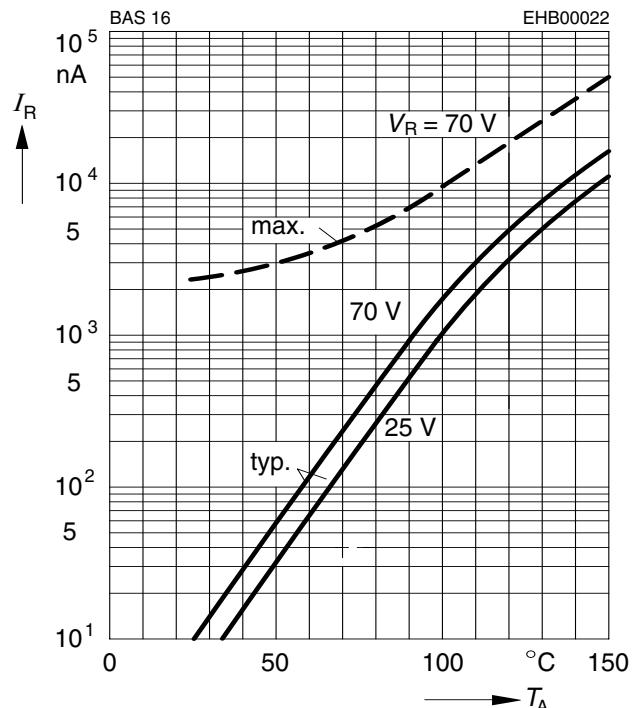
Oscilloscope: $R = 50\Omega$, $t_r = 0.35\text{ns}$,
 $C \leq 1\text{pF}$

Forward current $I_F = f(V_F)$

$T_A = 25^\circ\text{C}$



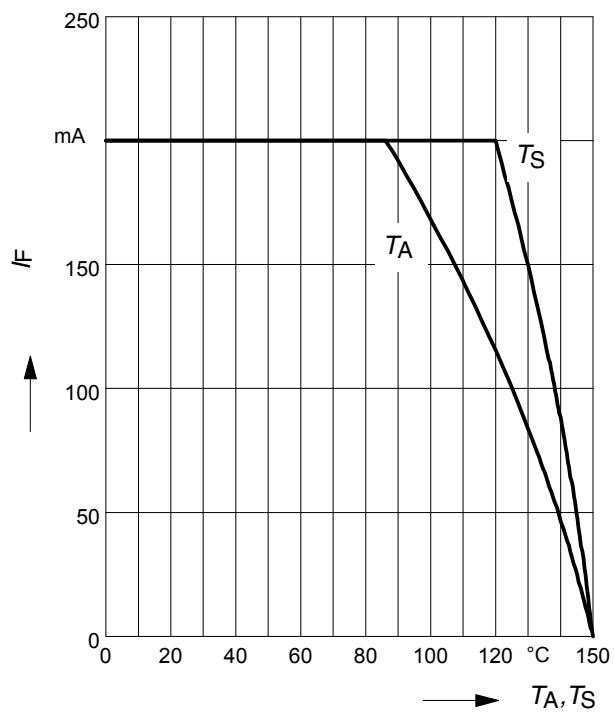
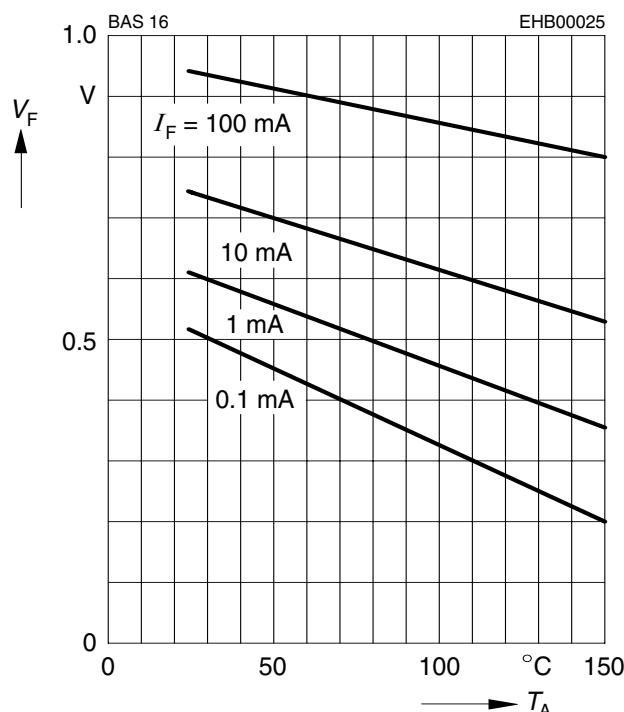
Reverse current $I_R = f(T_A)$



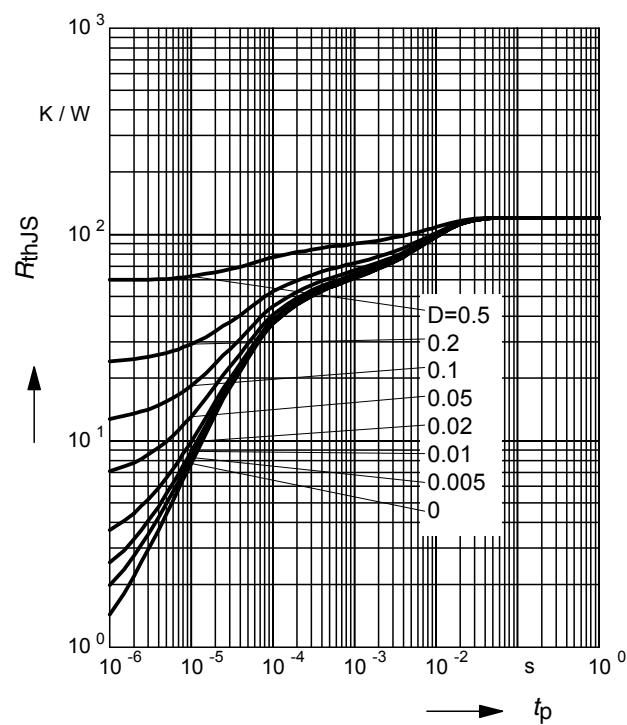
Forward voltage $V_F = f(T_A)$

Forward current $I_F = f(T_A^*; T_S)$

* Package mounted on epoxy



Permissible Pulse Load $R_{\text{THJS}} = f(t_p)$



Permissible Pulse Load

$$I_{\text{Fmax}} / I_{\text{FDC}} = f(t_p)$$

